Session Program

6-10 Sept 2010

Pixel2010 - International Workshop on Semiconductor Pixel Detectors for Particles and Imaging

Pixel Technologies III

Grindelwald, Switzerland

Thursday 9 September

4:00	Pixel Technologies III Session Location: Grindelwald, Switzerland Convener: HG. Moser
	14:00-14:20 SOI pixel detector with micro-bump bonding Speaker M. Motoyoshi
	14:20-14:40 Progress on 3D Integration Devices at Fermilab Speaker R. Yarema
	14:40-15:00 Metal and Hybrid TimePix Detectors Imaging Beams of Particles Speaker V. Pugatch
5:30	15:00-15:30 CiS - Your partner from development to production of silicon sensors Speaker R. Roeder